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# TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

# **TFT Display Module**

Part Number E24RG12432LWIM800-C

#### Overview:

- 2.4-inch TFT: 240x320 (42.72x60.26)
- 16/18- bit RGB
- 8/9/16/18-bit MCU
- 3-line/4-line Serial Interface
- White LED back-light

- Transmissive/ Normally Black
- Capacitive Touch Screen
- 450 NITS
- Controller: ST7789V
- RoHS Compliant



#### Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit and back-light unit. The resolution of a 2.4" TFT-LCD contains 240x320 pixels, and can display up to 65K/262K colors

#### **Features**

Low Input Voltage: 3.3V (TYP)

Display Colors of TFT LCD: 65K/262K colors

RGB Interface:

8/9/16/18-bit MCU; 16/18-bit RGB interface 3-line/4-line serial interface

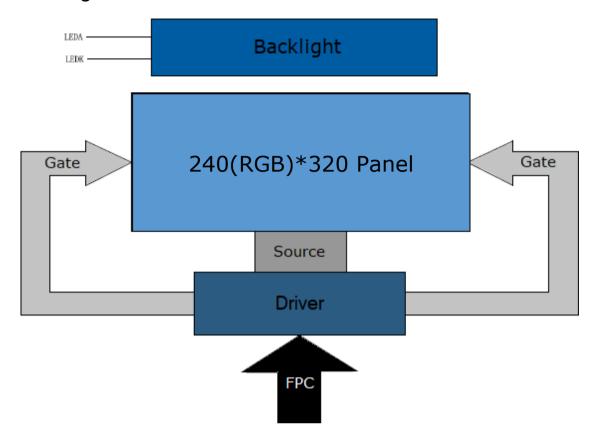
General Information Items			Note
Display area (AA)	36.72(H) *48.96(V) (2.4 inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K/262K	colors	-
Number of pixels	240(RGB)*320	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.151 (H) x 0.151 (V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ST7789V	-	-
Display mode	Transmissive/Normally Black	-	-
Operating temperature	-20∼+70	°C	-
Storage temperature	-30∼+80	°C	-

#### **Mechanical Information**

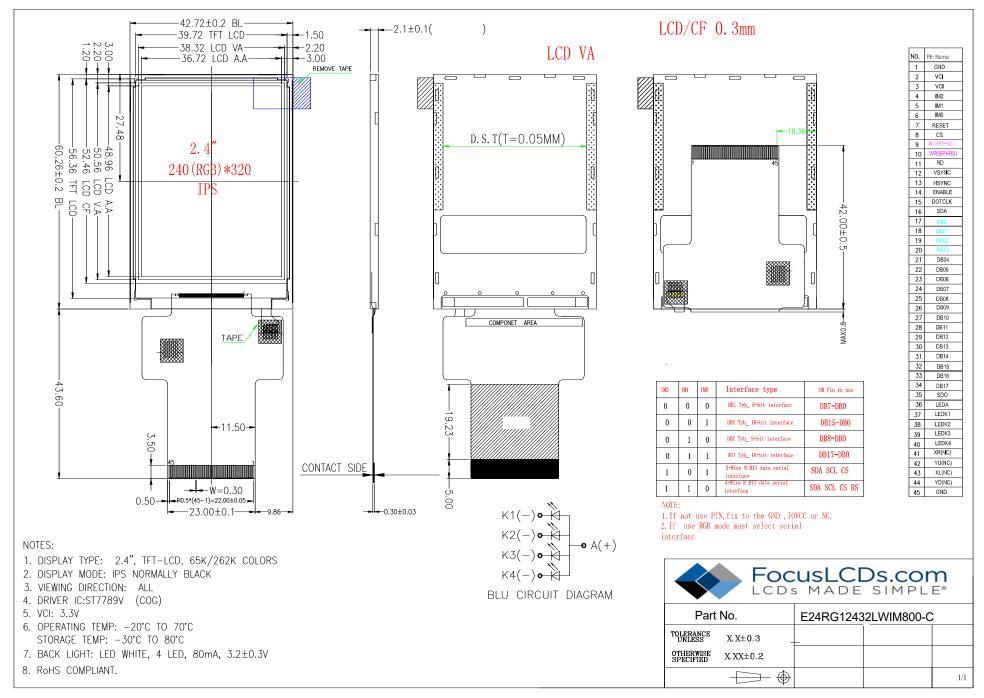
Item		Min	Тур.	Max	Unit	Note
	Horizontal(H)		42.72		mm	-
Module size	Vertical(V)		60.26		mm	-
3126	Depth(D)		2.1		mm	-
Weight			TBD		g	-



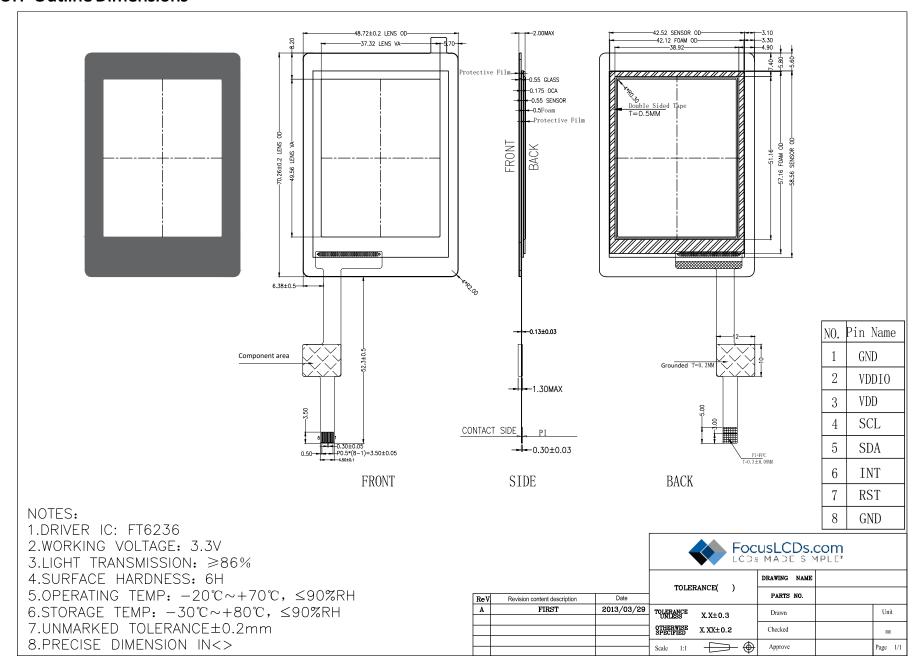
# 1. Block Diagram



#### 2. TFT Outline Dimensions



#### **CTP Outline Dimensions**



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# **3.** Input Terminal Pin Assignment Recommended TFT Connector: FH12S-45S-0.5SH(55)

Recommended TFT Connector: FH12S-45S-0.5SH(55) Recommended CTP Connector: FH12-8S-0.5SH(55)

RCCOIII	Recommended TFT Connector: FH12S-45S-0.5SH(55) Recommended CTP Connector: FH12-8S-0.5SH(55)								
NO.	Symbol	Description		I/O					
1	GND	Ground.		Р					
2	VCI	Supply voltage (3.3V)	Supply voltage (3.3V)						
3	VCI	Supply voltage (3.3V)							
4	IM2	MPI I parallel interface bus and seri	1PU parallel interface bus and serial interface select if use RGB interface must						
5	IM1	•	ect serial interface. Fix this pin at VCI and GND						
6	IM0	select serial interface. The this pin a	t ver and GND	I					
7	RESET	Reset signal of device and must be	applied to properly initialize the chip.	I					
8	CS	Chip select input pin ("Low" enable	). Fix this pin at VCI or GND when not in use.	I					
9	DC(SPLSCL)	• • •	n in parallel interface. This pin is used to be play data or parameter. D/CX='0': command at VCI or GND.	I					
10	WR(SPI- RS,SDA2)	Write enable in MCU parallel interf line serial interface. Second Data la If not used, please fix this pin at VC		I					
11	RD	Read signal and MCU read data at t Fix this pin at VCI or GND when not	5 5	1					
12	VSYNC	,	Frame synchronizing signal for RGB interface operation.  Fix this pin at VCI or GND when not in use.						
13	HSYNC	Line synchronizing signal for RGB in Fix this pin at VCI or GND when not	•	1					
14	ENABLE	Data enable signal for RGB interface Fix this pin at VCI or GND when not	•	I					
15	DOTCLK	Dot clock signal for RGB interface o Fix this pin at VCI or GND when not	•	I					
16	SDA1	Data lane in 1 data lane serial interior Data is latched on the rising edge o		ı					
17-34	DV0-DB17		us for MCU system and RGB interface mode.	I/O					
35	SDO	SPI interface output pin. Data on fa open.	lling edge of SCL signal. If not used, leave	0					
36	LEDA	Anode pin of backlight		Р					
37	LEDK1	Cathode pin of backlight		Р					
38	LEDK2	Cathode pin of backlight		Р					
39	LEDK3	Cathode pin of backlight		Р					
40	LEDK4	Cathode pin of backlight		Р					
41	XR(NC)	Touch panel right glass terminal		A/D					
42	YU(NC)	Touch panel bottom film terminal		A/D					
43	XL(NC)	Touch panel left glass terminal		A/D					
44	YD(NC)	Touch panel top film terminal		A/D					
45	GND	Ground		Р					



# 4. LCD Optical Characteristics

### 4.1 Optical Specifications

Item		Symbol	Condition	Min	Тур.	Max	Unit.	Note
Contrast R	atio	CR	Θ=0	640	800			(1)(2)
Transmittai (with polari		T(%)	Normal		4.65		%	(3)
Transmittaı (without pola		T(%)	viewing angle		14.6		%	(3)
	Rising	TR	aligie		16	21		(4)(4)
Response time	Falling	TF			19	24	msec	(1)(4)
Color gam	nut	S (%)			70		%	(5)
	White	wx		0.290	0.310	0.330		
	wille	WY		0.316	0.336	0.356		
	Red	RX		0.627	0.647	0.667		
Color Filter		RY		0.297	0.317	0.337		
Chromaticity	Cuaan	GX		0.255	0.275	0.295		(1)(5)
	Green	GY		0.562	0.582	0.602		
	Blue	Вх		0.120	0.140	0.160		
	Blue	Вү		0.068	0.088	0.108		
	Hor.	ΘL			80			
	пог.	ΘR			80			(1)(6)
Viewing angle	Vor	ΘU	CR>10		80			(1)(6)
	Ver.	ΘD			80			
Option View D	irection			FREE				(1)(6)

# 4.2 Measuring Condition

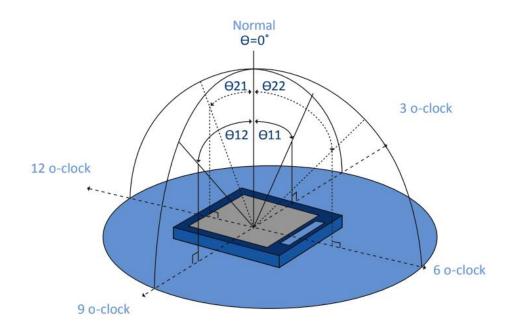
Measuring surrounding: dark room Ambient temperature: 25 ± 2°C

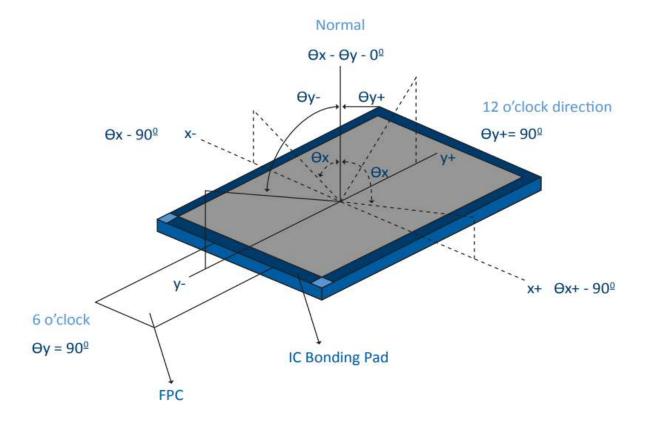
15min. warm-up time



#### **Optical Specification Reference Notes:**

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.



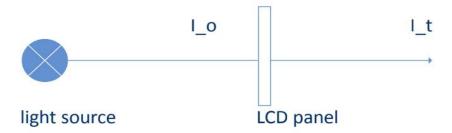




(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{Lw}{Ld}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving.



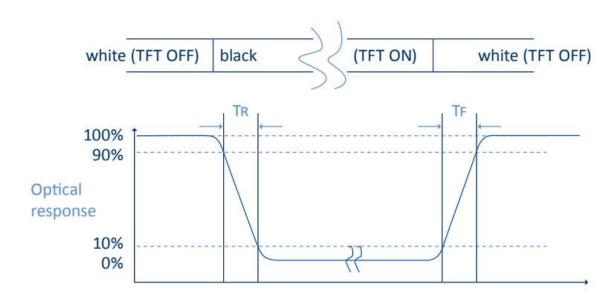
The transmittance is defined as:

$$Tr = \frac{It}{Io} \times 100\%$$

Io = the brightness of the light source.

It = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.





(5) Definition of Color Gamut: Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y),G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

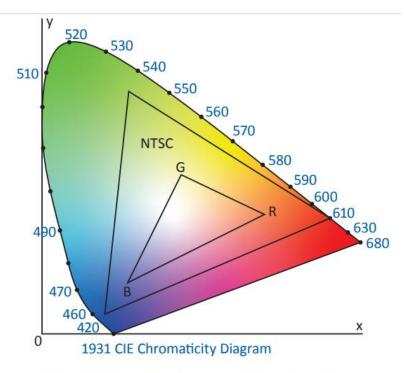
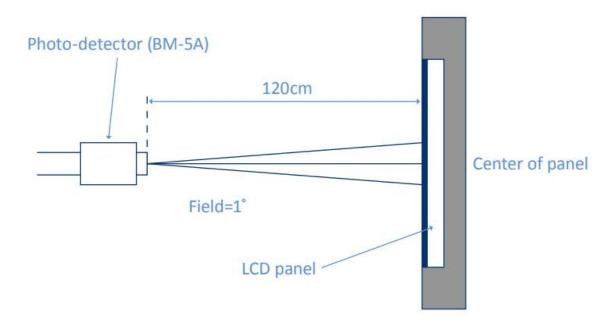


Fig. 1931 CIE chromacity diagram

Color gamut:  $S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$ 

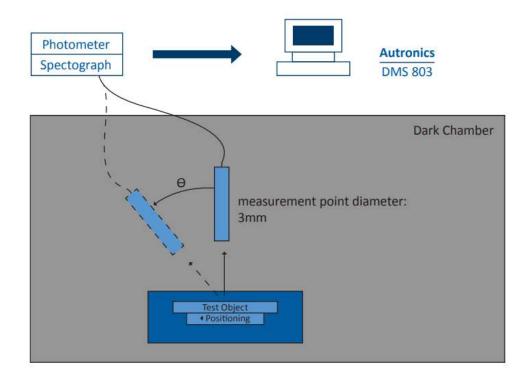
#### (6) Definition of Optical Measurement Setup:



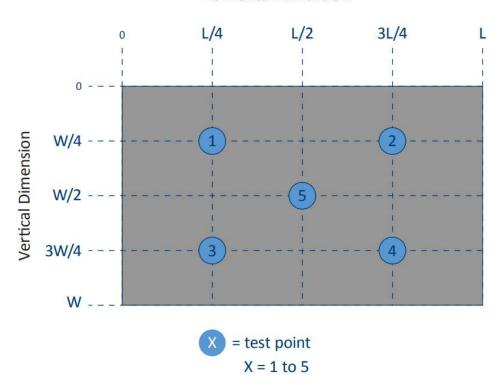


#### (6) Optical Measurement Setup Continued:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.



#### **Horizontal Dimension**





#### 5. Electrical Characteristics

#### 5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital Interface Supply Voltage	VDDIO	-0.3	4.6	
Operating temperature	TOP	-20	+70	°C
Storage temperature	TST	-30	+80	°C

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

#### **5.2** DC Electrical Characteristics

Characteristics	Symbol	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VDD	2.6	3.3	4.2	V	
Digital Interface Supply Voltage	VDDIO	1.65	1.8	4.2		
Normal Mode Current Consumption	IDD		8		mA	
Level input voltage	VIH	0.7 VDDIO		VDDIO	V	
Level input voitage	VIL	GND		0.3 VDDIO	V	
Level output voltage	VOH	0.8 VDDIO		VDDIO	V	
Level output voitage	VOL	GND		0.2 VDDIO	V	



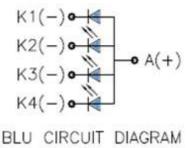
#### 5.3 LED Backlight Characteristics

ltem	Symbol	Min	Тур.	Max	Unit	Note
Forward Current	IF	60	80		mA	
Forward Voltage	VF		3.2		V	
LCM Luminance	LV	450			cd/m2	Note 3
LED lifetime	Hr	50000			hour	Note1 & 2
Uniformity	AVg	80			%	Note 3

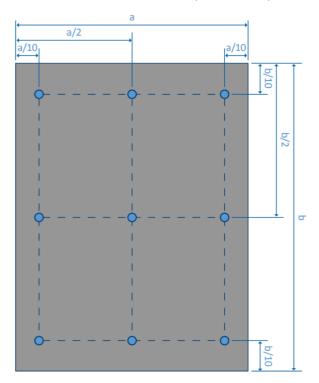
The back-light system is edge-lighting type with 4 chips White LED

Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition:  $Ta=25 \pm 3$  °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=80mA. The LED lifetime could be decreased if operating IL is larger than 80mA. The constant current driving method is suggested.



Note 3: Luminance Uniformity of these 9 points is defined as below:





#### 6. AC Characteristic

# 6.1 RGB Interface Timing Characteristics

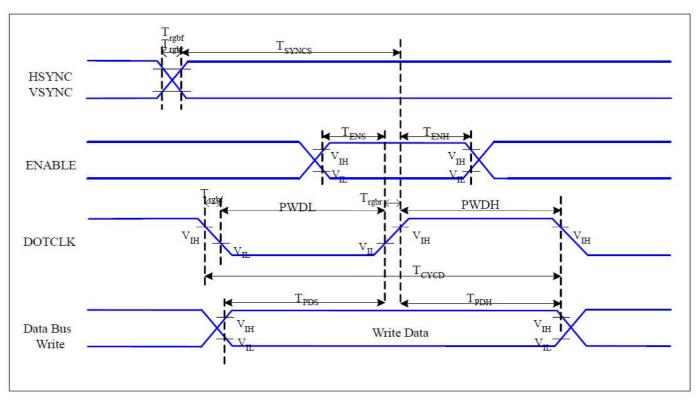


Figure 6.1: RGB Interface Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC, VSYNC	$T_{SYNCS}$	VSYNC, HSYNC Setup Time	15	-	ns	
ENADLE	$T_{ENS}$	Enable Setup Time	15	-	ns	
ENABLE	$T_{ENH}$	Enable Hold Time	15	-	ns	
	PWDH	DOTCLK High-level Pulse Width	15	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	15	-	ns	
DOTCLK	$T_{CYCD}$	DOTCLK Cycle Time	100	-	ns	
	$T_{RGHR}, T_{RGH}$	DOTCLK Rise/Fall Time	-	15	ns	
D.D.	$T_{PDS}$	PD Data Setup Time	15	-	ns	
DB	$T_{PDH}$	PD Data Hold Time	15	-	ns	

Table 6.1: 18/16 Bit RGB Interface Timing CharacteristicS

Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC, VSYNC	$T_{SYNCS}$	VSYNC, HSYNC Setup Time	15	-	ns	
ENABLE	$T_{ENS}$	Enable Setup Time	15	-	ns	
ENABLE	$T_{ENH}$	Enable Hold Time	15	-	ns	
	PWDH	DOTCLK High-level Pulse Width	15	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	15	-	ns	
DOTCER	$T_{CYCD}$	DOTCLK Cycle Time	100	-	ns	
	$T_{RGHR}$ , $T_{RGH}$	DOTCLK Rise/Fall Time	-	15	ns	
D.B.	$T_{PDS}$	PD Data Setup Time	15	-	ns	
DB	$T_{PDH}$	PD Data Hold Time	15	-	ns	

Table 6.2: 6 Bit RGB Interface Timing Characteristics



#### 6.2 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

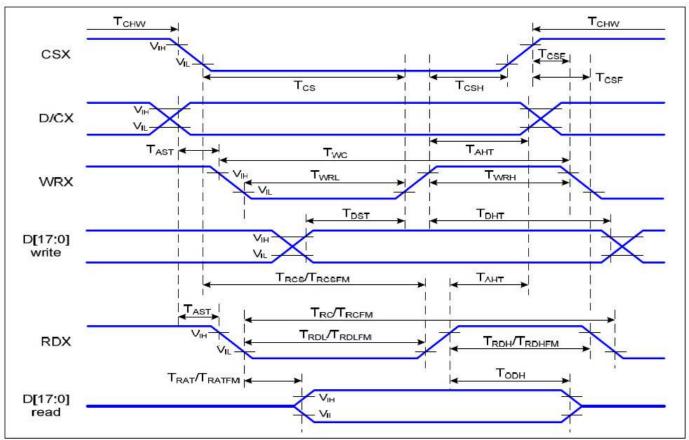


Figure 6.2: 8080 MCU Parallel Interface Timing Diagram

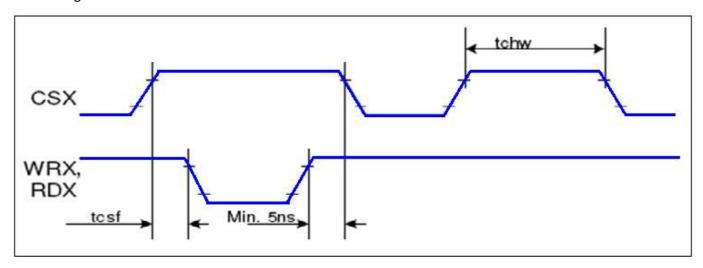
Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T <sub>AST</sub>	Address setup time	0	-	ns	
Б/СК	T <sub>AHT</sub>	Address hold time (Write/Read)	0	-	ns	
	$T_CHW$	Chip select "H" pulse width	0	-	ns	
	T <sub>CS</sub>	Chip select setup time (Write)	15	-	ns	
CSX	$T_RCS$	Chip select setup time (Read ID)	45	-	ns	
CSA	$T_{RCSFM}$	Chip select setup time (Read FM)	355	-	ns	
	$T_{CSF}$	Chip select wait time (Write/Read)	10	-	ns	
	$T_{CSH}$	Chip select hold time	10	-	ns	
	$T_WC$	Write cycle	66	-	ns	
WRX	$T_{WRH}$	Control pulse "H" duration	15	-	ns	
	$T_{WRL}$	Control pulse "L" duration	15		ns	
	$T_RC$	Read cycle (ID)	160	-	ns	When read ID
RDX (ID)	$T_{RDH}$	Control pulse "H" duration (ID)	90	-	ns	data
	$T_{RDL}$	Control pulse "L" duration	45	-	ns	uata
	$T_{RCFM}$	Read cycle (FM)	450	-	ns	
RDX (FM)	$T_{RDHFM}$	Control pulse "H" duration (FM)	90	-	ns	When read from
, ,	$T_{RDLFM}$	Control pulse "L" duration (FM)	355	-	ns	frame memory
D[17:0]	T <sub>DST</sub>	Write data setup time	10	-	ns	
D[15:0], D[8:0],	T <sub>DHT</sub>	Write data hold time	10	-	ns	For max CL=30pF
	T <sub>RAT</sub>	Read access time (ID)	-	40	ns	
D[7:0]	T <sub>RATFM</sub>	Read access time (FM)	-	340	ns	For min CL=8pF
	$T_{ROD}$	Output disable time	20	80	ns	

Table 6.3: 8080 MCU Parallel Interface Characteristics

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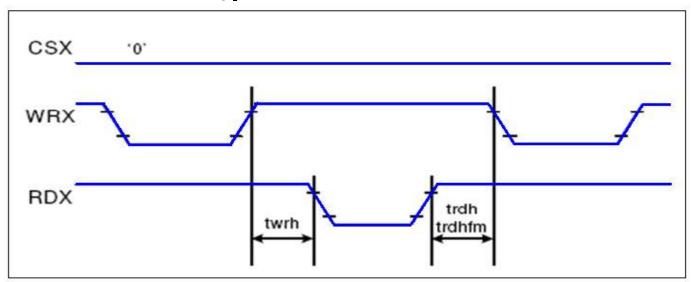


#### CSX timings:

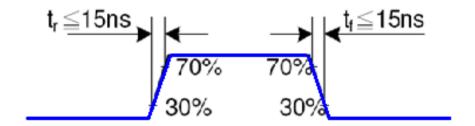


Note: Logic high and low levels are specified as 30% and 70% of IOVCC for input signals.

#### Write to read or read to write timings:



Note: Ta = -30 to 70 C, IOVCC = 1.65V to 2.8V, VCI = 2.6V to 3.3V, GND = 0V.





# 6.3 Display Serial Interface Characteristics (3-line SPI system)

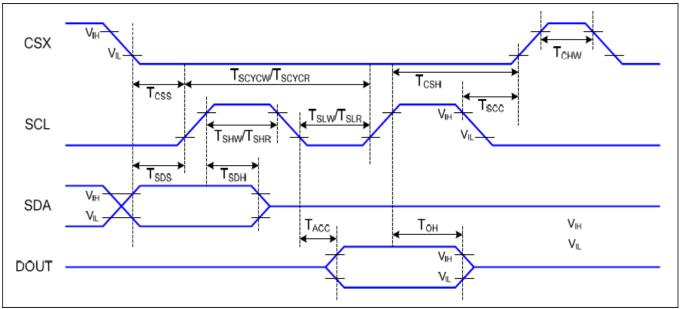


Figure 6.3: 3-Line Serial Interface Timing Diagram

VDDI = 1.64 to 3.3V, VDD = 2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T <sub>CSS</sub>	Chip select setup time (write)	20		ns	
	T <sub>CSH</sub>	Chip select hold time (write)	20		ns	
	T <sub>CSS</sub>	Chip select setup time (read)	60		ns	
CSX	T <sub>SCC</sub>	Chip select hold time (read)	65		ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
	T <sub>SCYCW</sub>	Serial clock cycle (write)	100		ns	
	T <sub>SHW</sub>	SCL "H" pulse width (write)	40		ns	
CCI	T <sub>SLW</sub>	SCL "L" width (write)	40		ns	
SCL	T <sub>SCYCR</sub>	Serial clock cycle (read)	150		ns	
	T <sub>SHR</sub>	SCL "H" pulse width (read)	60		ns	
	T <sub>SLR</sub>	SCL "L" pulse width (read)	60		ns	
CDA (DINI)	T <sub>SDS</sub>	Data setup time	30		nc	
SDA (DIN)	T <sub>SDH</sub>	Data hold time	30		ns	
	T <sub>ACC</sub>	Access time	10			For max
DOUT	Тон	Output disable time	10	50	ns	CL=30pF For min CL=8pF

Table 6.4: 3-Line Serial Interface Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals



# 6.4 Display Serial Interface Characteristics (4-line SPI serial)

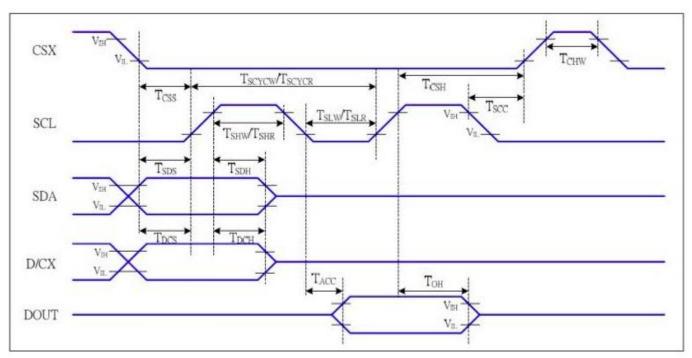


Figure 6.4: 4-Line Serial Interface Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T <sub>CSS</sub>	Chip select setup time (write)	40		ns	
	T <sub>CSH</sub>	Chip select hold time (write)	40		ns	
CSX	T <sub>CSS</sub>	Chip select setup time (read)	40		ns	
	T <sub>SCC</sub>	Chip select hold time (read)	40		ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
	T <sub>SCYCW</sub>	Serial clock cycle (write)	100		ns	write command 9
	T <sub>SHW</sub>	SCL "H" pulse width (write)	40		ns	write command &
SCL	T <sub>SLW</sub>	SCL "L" width (write)	40		ns	data ram
SCL	T <sub>SCYCR</sub>	Serial clock cycle (read)	150		ns	was disamenan di O
	T <sub>SHR</sub>	SCL "H" pulse width (read)	60		ns	read command &
	T <sub>SLR</sub>	SCL "L" pulse width (read)	60		ns	data ram
D/CX	$T_{DCS}$	D/CX setup time	10		ns	
D/CX	T <sub>DCH</sub>	D/CX hold time	10		ns	
CDA (DINI)	T <sub>SDS</sub>	Data setup time	30		ns	
SDA (DIN)	T <sub>SDH</sub>	Data hold time	30		ns	
	T <sub>ACC</sub>	Access time	10		ns	For max CL=30pF
DOUT	T <sub>OH</sub>	Output disable time	10	50	ns	For min CL=8pF

Table 6.5: 4-Line Serial Interface Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



#### 6.5 Reset Timing

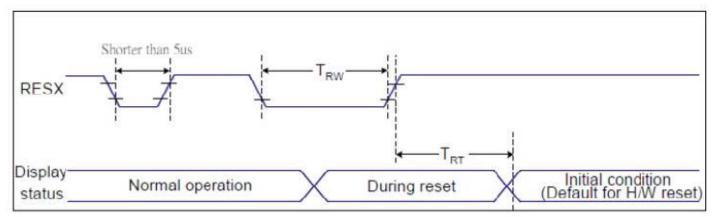


Figure 6.5: Reset Timing Diagram

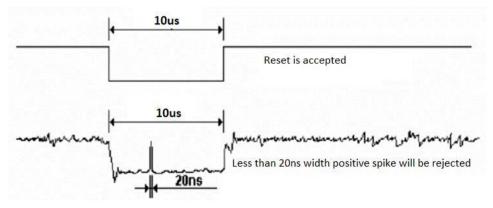
Related Pins	Symbol	Parameter	Min	Max	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1,5)	ms
				120 (Note 1, 6, 7)	ms

#### Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action	
Shorter than 5us	Reset Rejected	
Longer than 9us	Reset	
Between 5us and 9 us	Reset starts	

- 3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



#### 7. Cautions and Handling Precautions

#### 7.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static; it may cause damage to the CMOS ICs.
- 9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

#### 7.2 Storage and Transportation

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the TFT-LCD module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.